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Kiwamu Takehisa
Editor

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The CID Number appears on each page of the manuscript. The complete citation is used on the first page, and an abbreviated version on subsequent pages.

Contents

vii	<i>Authors</i>
ix	<i>Conference Committee</i>

SESSION 1	FPD PHOTOMASKS I: EQUIPMENT TOOLS AND PELLICLE
10454 02	Development of high sensitivity and high speed large size blank inspection system LBIS [10454-43]
10454 03	Influence of the pellicle for FPD for i-line single wavelength exposure [10454-23]
SESSION 2	FPD PHOTOMASKS II: MATERIAL AND PROCESS
10454 04	New PSM optimized for stable resolution of fine holes in FPD [10454-9]
10454 05	Shin-Etsu super-high-flat substrate for FPD panel photomask [10454-11]
SESSION 3	USE OF GPU IN MASK MAKING I
10454 06	GPU: the biggest key processor for AI and parallel processing (Keynote Paper) [10454-19]
10454 07	Model-based MPC enables curvilinear ILT using either VSB or multi-beam mask writers [10454-33]
10454 08	EUV modeling in the multi-beam mask writing era [10454-38]
10454 09	Simulation-based MDP verification for leading-edge masks [10454-30]
SESSION 4	USE OF GPU IN MASK MAKING II
10454 0A	eBeam initiative survey reports confidence in EUV and multi-beam technology (Invited Paper) [10454-22]
10454 0B	Electron beam lithographic modeling assisted by artificial intelligence technology [10454-41]
10454 0C	Mask CD relationship to temperature at the time backscatter is received [10454-35]
10454 0D	GPU-accelerated inline linearity correction: pixel-level dose correction (PLDC) for the MBM-1000 [10454-34]

SESSION 5	WRITING TECHNOLOGIES
10454 0E	Multi-beam mask writer MBM-1000 [10454-42]
SESSION 6	EDA & MDP
10454 0G	Cycle time reduction by Html report in mask checking flow [10454-10]
10454 0H	Data preparation in the age of curvilinear patterns [10454-29]
SESSION 7	LITHOGRAPHY RELATED TECHNOLOGIES
10454 0I	Accurate lithography simulation model based on convolutional neural networks [10454-25]
10454 0J	MTO-like reference mask modeling for advanced inverse lithography technology patterns [10454-36]
SESSION 8	PROCESS
10454 0K	Effects of hard mask etch on final topography of advanced phase shift masks [10454-5]
10454 0L	Etch bias inversion during EUV mask ARC etch [10454-14]
SESSION 10	EUV MASKS I
10454 0M	Overcoming EUV mask blank defects: what we can, and what we should (Invited Paper) [10454-37]
10454 0N	Application of EUV dark field image for EUVL mask fabrication [10454-26]
SESSION 11	EUV MASKS II
10454 0O	First light and results on EBL2 [10454-17]
SESSION 12	EUV MASKS III
10454 0P	EUV repair process optimization and integration [10454-15]
SESSION 13	NIL
10454 0Q	Application of EB repair for nanoimprint lithography template [10454-27]

10454 OR **Improved particle control for high volume semiconductor manufacturing for nanoimprint lithography** [10454-20]

POSTER SESSION: MATERIALS OF AND FOR PHOTOMASKS

10454 OS **Quartz 9-inch size mask blanks for ArF PSM (Phase Shift Mask)** [10454-39]

POSTER SESSION: PROCESS

10454 OT **Mask crosstalk defect between develop to etch process** [10454-3]

10454 OU **Stabilize OMOG photomask post-repair CD variation by cleaning strategy and post-repair treatment** [10454-4]

POSTER SESSION: METROLOGY TOOLS AND TECHNOLOGIES

10454 OV **LMS IPRO: enabling accurate registration metrology on SiN-based phase-shift masks** [10454-24]

10454 OW **Old and new techniques mixed up into optical photomask measurement method** [10454-16]

POSTER SESSION: REPAIRING TOOLS AND TECHNOLOGIES

10454 OX **How smart is your BEOL? productivity improvement through intelligent automation** [10454-40]

POSTER SESSION: NIL

10454 OY **The capability of measuring cross-sectional profile for hole patterns in nanoimprint templates using small-angle x-ray scattering** [10454-28]

POSTER SESSION: FPD PHOTOMASKS MATERIAL AND PROCESS

10454 OZ **Application of advanced structure to multi-tone mask for FPD process** [10454-12]

POSTER SESSION: MASK/LITHOGRAPHY RELATED TECHNOLOGIES IN ACADEMIA

10454 10 **Fabrication of cylindrical micro-parts using synchronous rotary scan-projection lithography and chemical etching** [10454-6]

10454 11 **Electrolytic etching of fine stainless-steel pipes patterned by laser-scan lithography** [10454-8]

- 10454 12 **Research on fabrication of resist mold patterns for electroplating** [10454-7]
- 10454 13 **Observation of EUVL mask using coherent EUV scatterometry microscope with high-harmonic-generation EUV source** [10454-2]
- 10454 14 **Exposure characteristics of positive tone electron beam resist containing *p*-chloro-*a*-methylstyrene** [10454-18]

Authors

Numbers in the index correspond to the last two digits of the seven-digit citation identifier (CID) article numbering system used in Proceedings of SPIE. The first five digits reflect the volume number. Base 36 numbering is employed for the last two digits and indicates the order of articles within the volume. Numbers start with 00, 01, 02, 03, 04, 05, 06, 07, 08, 09, 0A, 0B...0Z, followed by 10-1Z, 20-2Z, etc.

Aghili, Ali, 0R	Iso, Hiroyuki, 0S
Asada, Hironori, 14	Isozaki, Tatsuya, 0S
Azuma, Hisanobu, 0R	Ito, Kaiki, 10
Baessler, Martin, 0K	Ito, Yoshiyasu, 0Y
Baji, Toru, 06	Itoh, Masamitsu, 0Q
Bayle, Sébastien, 0H	Iwakuma, Minako, 14
Bender, Markus, 0P	Jeon, Chan-Uk, 0J
Bowhill, Amanda, 0G	Jeong, Jin-Woong, 0Z
Broadbent, Bill, 0J	Jeong, Woo-Gun, 0Z
Buettner, Alexander, 0V	Jonckheere, Rik, 0M
Chang, Vic, 0U	Jones, Chris E., 0R
Chen, Jian-Cheng, 0G	Kageyama, Kagehiro, 0S
Chishima, Tatsuya, 0S	Kamikubo, Takashi, 0B, 0C
Choi, Jin, 0R	Kanai, Shuichiro, 0S
Choi, Sang-Soo, 0Z	Kato, Takenori, 02
Choo, Min, 0J	Kawanishi, Arata, 0S
Chung, Donghoon, 0J	Kerkhof, Peter, 0O
Deng, Erwin, 0G	Kim, Byung-Gook, 0J
Deutz, Alex, 0O	Kim, Kyu-Sik, 0Z
Egodage, Kokila, 0X	Kim, Soonho, 0J
Emoto, Keiji, 0R	Kimura, Taiki, 0I
Fang, Xiang, 0G	Kishimura, Yukiko, 14
Figueiro, Thiago, 0H	Koster, Norbert, 0O
Fujikawa, Takashi, 03	Kronmiller, Tom, 0C
Fujimura, Aki, 07, 08, 09, 0A, 0C, 0D	Kumada, Ai, 0Q
Fukui, Jumpei, 0W	Kusunose, Haruhiko, 02
Garetto, Anthony, 0X	Lajn, Alexander, 0K, 0L, 0P
Guthrie, Bill, 0C	Lee, Dong-Heok, 0Z
Hagihara, Kazuki, 0Y	Lee, Hong-Jen, 0T
Hagiwara, Kazuyuki, 09	Lee, Rachel, 0G
Han, Runyuan, 0V	Liao, Hung-Yueh, 0G
Hara, Daisuke, 07	Lin, Ling-Chieh, 0G
Harada, Daijitsu, 05	LoPresti, Patrick, 0J
Harada, Tetsuo, 13	Lu, Min-Ying, 0G
Harashima, Noriyuki, 0S	Ma, Shou-Yuan, 0G
Hayase, Michihiko, 04	Maeda, Toshihiro, 0R
Hayashi, Naoya, 0Y	Mamezaki, Daiki, 13
Hirai, Mitsuo, 02	Martin, Luc, 0H
Hirano, Masakatsu, 03	Maruyama, Kimiyuki, 03
Hirano, Takashi, 0Q	Maruyama, Yuji, 03
Hirayama, Sadayuki, 03	Masuda, Yukihiko, 0C, 0D
Horiuchi, Toshiyuki, 10, 11, 12	Matsumoto, Hironobu, 0D
Hortenbach, Olga, 0K	Matsumoto, Hiroshi, 0E
Hoshino, Ryoichi, 14	Matsunawa, Tetsuaki, 0I
Hsu, Yuan, 0T	Matsuoka, Yoichi, 0R
Huang, Kuang, 0U	Milléquant, Matthieu, 0H
Hur, Jiuk, 0J	Miura, Satoru, 0B
Imashiki, Nobuhisa, 04	Mizuno, Makoto, 0R
Ishitsuka, Youkou, 05	Molkenboer, Freek, 0O

Moon, Jongin, 0J
 Moriizumi, Koichi, 02
 Morishita, Keiko, 0Q
 Muilwijk, Pim, 0O
 Mulckhuysen, Wouter, 0O
 Nagata, Yutaka, 13
 Nakagawa, Kazuki, 0R
 Nakahara, Tatsunori, 03
 Nakayama, Takahiro, 0R
 Nakayamada, Noriaki, 0B, 0C, 0D
 Nesládek, Pavel, 0P
 Nijland, Bjorn, 0O
 Nishida, Yuhta, 12
 Nishimura, Rieko, 0B
 Nojima, Shigeki, 0I
 Nomura, Haruyuki, 0B
 Ochiai, Shunsuke, 14
 Ogata, Kiyoshi, 0Y, 0Y
 Ohara, Shinobu, 02
 Ohtoshi, Kenji, 0E
 Omote, Kazuhiko, 0Y
 Osanai, Makoto, 0W
 Pang, Leo, 09
 Pang, Linyong, 07
 Park, Jongju, 0J
 Pearman, Ryan, 08, 09, 0C, 0D
 Pomerantsev, Michael, 07, 09
 Postnikov, Sergei, 0H
 Roeth, Klaus-Dieter, 0V
 Rolff, Haiko, 0K, 0L
 Russell, Gordon, 0G
 Sagara, Tomoya, 11
 Schedel, Thorsten, 0P
 Schiavone, Patrick, 0H
 Schulz, Kristian, 0X
 Shen, Ming-Feng, 0G
 Shen, Vincent, 0U
 Shimizu, Kouta, 12
 Shirali, Nagesh, 0C, 0D
 Son, Suein, 0J
 Song, Jin-Han, 0Z
 Sonoda, Manae, 14
 Steigerwald, Hendrik, 0V
 Su, Bo, 07, 09
 Suzuki, Yuta, 10
 Syrel, Oleg, 09
 Tabbone, Gilles, 0X
 Tachibana, Yusaku, 0W
 Takabayashi, Yukio, 0R
 Takahashi, Hiroshi, 11
 Takatsukasa, Yutetsu, 07
 Takayama, Tomohiro, 14
 Takeuchi, Masaki, 05
 Tamura, Takao, 0E
 Tani, Noriko, 03
 Taniguchi, Rikiya, 0Y
 te Sligte, Edwin, 0O
 Tiphine, Charles, 0H
 Tsai, Jenny, 0G
 Tsai, Joe, 0G

Tzeng, Josh, 0U
 Ueba, Ryosuke, 0D
 van der Walle, Peter, 0O
 van Putten, Michel, 0O
 Vu, Hien, 0G
 Wang, Sonny, 0J
 Watabe, Atsushi, 05
 Watanabe, Hidehiro, 0N
 Watanabe, Takeo, 13
 Watanabe, Yuki, 0I
 Willis, Jan, 0A
 Wistrom, Richard, 0L
 Xue, Shan, 0J
 Yagawa, Keisuke, 0Q
 Yamanaka, Eiji, 0Y
 Yamane, Takeshi, 0N
 Yamashita, Hiroshi, 0E
 Yang, Chuen-Huei, 0G
 Yano, Kohei, 03
 Yasui, Kenichi, 0D
 Yonekawa, Masami, 0R
 Yoshida, Akinori, 02
 Yoshikawa, Ryoji, 0Q
 Yoshikawa, Yutaka, 04
 Yun, Sang-Pil, 0Z
 Zable, Harold, 08, 0C, 0D

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Ichiro Kagami, Sony Semiconductor Manufacturing Corporation (Japan)
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- 3 Use of GPU in Mask Making I
Kiwamu Takehisa, Lasertec Corporation (Japan)
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- 4 Use of GPU in Mask Making II
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- 5 Writing Technologies
Hironobu Manabe, JEOL Ltd. (Japan)
Uwe Behringer, UBC Microelectronics (Germany)
- 6 EDA & MDP
Kazuyuki Hagiwara, D2S, K.K. (Japan)
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- 7 Lithography Related Technologies
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- 8 Process
Hidemichi Imai, Dai Nippon Printing Company, Ltd. (Japan)
Paul W. Ackmann, GLOBALFOUNDRIES Corporation (USA)
- 10 EUV Masks I
Tsutomu Shoki, HOYA Corporation (Japan)
Jo Finders, ASML (The Netherlands)
- 11 EUV Masks II
Tsukasa Abe, Dai Nippon Printing Company, Ltd. (Japan)
Rik Jonckheere, Imec (Belgium)
- 12 EUV Masks III
Junji Miyazaki, ASML Japan (Japan)
Guojing Zhang, Intel Corporation (USA)
- 13 NIL
Akihiko Ando, Toshiba Corporation (Japan)
Douglas Resnick, Canon Nanotechnologies, Inc. (USA)